

# 2A/1A Fixed Output LDO Regulators BAXXDD0T Series BAXXCC0T Series BAXXCC0FP Series

# 2A/1A Fixed Output LDO Regulators With Shutdown Swicth

BAxxDD0WT Series BAxxDD0HFP Series BAxxCC0WFP Series

#### General Description

Standard Fixed Output LDO Regulators are low-saturation regulators, available for output s up to 2A / 1A. ROHM has a wide output voltage range and package lineup with and without shutdown switches. This IC has a built-in over-current protection circuit that prevents the destruction of the IC due to output short circuits, a thermal shut-down circuit that protects the IC from damage due to overloading and an over-voltage protection circuit that protects the IC from surges generated in the power supply line of the IC.

#### Features

- ±1% highly accurate output voltage (BAxxDD0xx)
- Low saturation with PNP output
- Built-in over-current protection circuit that prevents the destruction of the IC due to output short circuits
- Built-in thermal shutdown circuit for protecting the IC from damage due to overloading
- Built-in over- voltage protection circuit that prevents the destruction of the IC due to power supply surges

#### Nev Specification

Input Power Supply Voltage: 25V (Max.) Output voltage type: Fixed BAxxDD0xx series 2A (Max.) Output current: BAxxCC0xx series 1A (Max.) Shutdown current: 0μA(Typ.) -40°C to +125°C Operating temperature range:

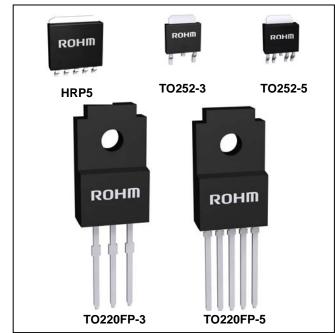
#### Applications

Used in DSP power supplies for DVD and CD players, FPDs, televisions, personal computers or any other consumer device

#### Packages

HRP5 TO252-3 TO252-5 TO220FP-3 TO220FP-5

W (Typ.) x D (Typ.) x H (Max.) 9.395mm x 10.54mm x 2.005mm 6.50 mm x 9.50mm x 2.50 mm 6.50 mm x 9.50mm x 2.50 mm 10.00 mm x 30.50mm x 4.60 mm 10.00 mm x 30.50mm x 4.60 mm



#### Lineup matrix

■1A output BAxxCC0xx Series

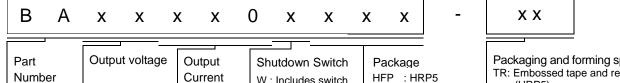
Part Number		Output voltage (V)									Packago
Part Number	3.0	3.3	5.0	6.0	7.0	8.0	9.0	10.0	12.0	15.0	Package
BAxxCC0WT	0	0	0	_	0	0	0	0	0	_	TO220FP-5
BAxxCC0WFP	_	0	0	0	0	0	0	_	0	_	TO252-5
BAxxCC0T	0	0	0	0	0	0	0	0	0	0	TO220FP-3
BAxxCC0FP	0	0	0	0	0	0	0	0	0	0	TO252-3

12A output BAxxDD0xx Series

Part Number				Dookogo						
Part Number	1.5	1.8	2.5	3.0	3.3	5.0	9.0	12.0	16.0	Package
BAxxDD0WT	0	0	0	0	0	0	0	0	0	TO220FP-5
BAxxDD0WHFP	0	0	0	0	0	0	0	0	0	HRP5
BAxxDD0T	0	0	0	0	0	0	0	0	0	TO220FP-3

OProduct structure: Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

Ordering Information



W: Includes switch None: without switch CC0:1A : TO252-5 DD0:2A : TO252-3 Т : TO220FP-5 : TO220FP-3 Packaging and forming specification TR: Embossed tape and reel (HRP5)

E2: Embossed tape and reel (TO252-3,TO252-5) None : Container Tube (TO220FP-3,TO220FP-5)

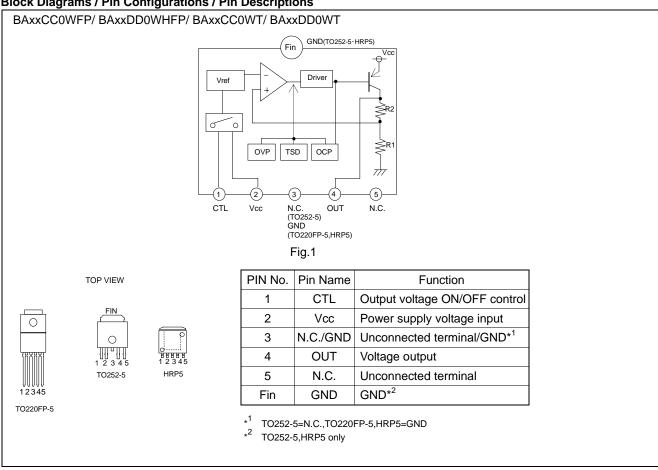
#### Lineup

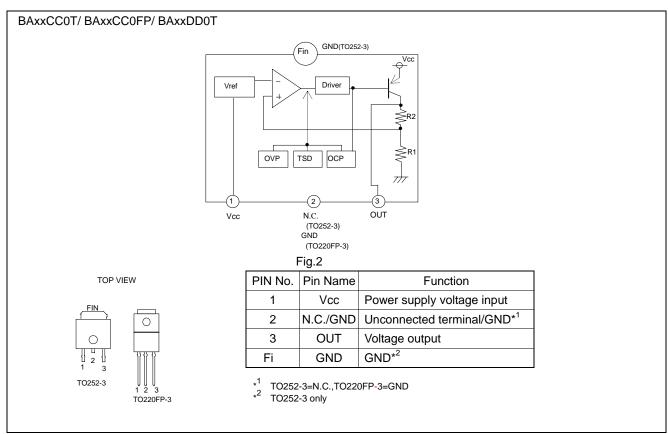
■1A output BAxxCC0xx Series

Maximum output current (Max.)	Shutdown Switch	Pac	kage	Output voltage(Typ.)	Orderable Part Number
				3.3V	BA033CC0WFP-E2
				5.0V	BA05CC0WFP-E2
				6.0V	BA06CC0WFP-E2
		TO252-5	Reel of 2000	7.0V	BA07CC0WFP-E2
				8.0V	BA08CC0WFP-E2
				9.0V	BA09CC0WFP-E2
				12.0V	BAJ2CC0WFP-E2
	With Switch			3.0V	BA03CC0WT
				3.3V	BA033CC0WT
				5.0V	BA05CC0WT
		TOSSOED F	Tub = = 4 500	7.0V	BA07CC0WT
		TO220FP-5	Tube of 500	8.0V	BA08CC0WT
				9.0V	BA09CC0WT
				10.0V	BAJ0CC0WT
				12.0V	BAJ2CC0WT
			Reel of 2000	3.0V	BA03CC0FP-E2
				3.3V	BA033CC0FP-E2
1A				5.0V	BA05CC0FP-E2
				6.0V	BA06CC0FP-E2
		TO252.2		7.0V	BA07CC0FP-E2
		TO252-3		8.0V	BA08CC0FP-E2
				9.0V	BA09CC0FP-E2
				10.0V	BAJ0CC0FP-E2
				12.0V	BAJ2CC0FP-E2
	No oviitab			15.0V	BAJ5CC0FP-E2
	No switch			3.0V	BA03CC0T
				3.3V	BA033CC0T
				5.0V	BA05CC0T
				6.0V	BA06CC0T
		TOSSOED	Tubo of 500	7.0V	BA07CC0T
		TO220FP-3	Tube of 500	8.0V	BA08CC0T
				9.0V	BA09CC0T
				10.0V	BAJ0CC0T
				12.0V	BAJ2CC0T
				15.0V	BAJ5CC0T

Maximum output current (Max.)	Shutdown Switch	Pac	kage	Output voltage(Typ.)	Orderable Part Number			
				1.5V	BA15DD0WT			
				1.8V	BA18DD0WT			
				2.5V	BA25DD0WT			
				3.0V	BA30DD0WT			
		TO220FP-5	Tube of 500	3.3V	BA33DD0WT			
				5.0V	BA50DD0WT			
				9.0V	BA90DD0WT			
				12.0V	BAJ2DD0WT			
	With Switch			16.0V	BAJ6DD0WT			
	With Switch			1.5V	BA15DD0WHFP-TR			
				1.8V	BA18DD0WHFP-TR			
				2.5V	BA25DD0WHFP-TR			
				3.0V	BA30DD0WHFP-TR			
2A					HRP5	Reel of 2000	3.3V	BA33DD0WHFP-TR
					5.0V	BA50DD0WHFP-TR		
				9.0V	BA90DD0WHFP-TR			
		HRP5					12.0V	BAJ2DD0WHFP-TR
				1.5V 1.8V 2.5V 3.0V 3.3V 5.0V 9.0V 12.0V 16.0V 1.5V 1.8V 2.5V 3.0V 3.3V	BAJ6DD0WHFP-TR			
				1.5V	BA15DD0T			
				1.8V	BA18DD0T			
				2.5V	BA25DD0T			
				3.0V	BA30DD0T			
No switch	No switch	TO220FP-3	Tube of 500	3.3V	BA33DD0T			
				5.0V	BA50DD0T			
				9.0V	BA90DD0T			
				12.0V	BAJ2DD0T			
				16.0V	BAJ6DD0T			

#### ●Block Diagrams / Pin Configurations / Pin Descriptions

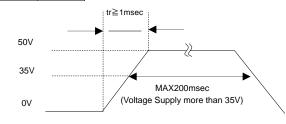




● Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Input Power Supply Voltage*1	ut Power Supply Voltage <sup>*1</sup> V <sub>CC</sub>		V
		2300(HRP5)	
Power Dissipation*2	D4	1300(TO252-5)	mW
Power Dissipation	Pd	1200(TO252-3)	
		2000(TO220FP-3,5)	
Operating Temperature Range	Topr	-40 to +125	°C
Ambient Storage Temperature	Tstg	-55 to +150	°C
Junction Temperature	Tj <sub>MAX.</sub>	+150	°C
Output Control Terminal Voltage*3	Vctl	-0.3 to +Vcc	V
Voltage Applied to the Tip *4	VCC peak	+50	V

<sup>\*1</sup> Must not exceed Pd



● Recommended Operating Ratings (Ta=25°C)

Parameter		Symbol		Unit			
Falaiii	etei	Symbol	Min.	Ratings Typ. — — — —	Max.	Offic	
Input	BAxxCC0xx	V	4.0	_	25.0	V	
Power Supply Voltage	BAxxDD0xx	V <sub>CC</sub>	3.0		25.0	V	
Output Current	BAxxCC0xx			_	1	Α	
Output Current  BAxxDD0xx		- lo	_	_	2	Α	
Output Control Terminal Voltage		Vctl	0	_	V <sub>CC</sub>	V	

<sup>\*2</sup> HRP5: In cases in which Ta≥25°C when a 70mm×70mm×1.6mm glass epoxy board is used, the power is reduced by 18.4 mW/°C.

TO252FP-3: In cases in which Ta≥25°C when a 70mm×70mm×1.6mm glass epoxy board is used, the power is reduced by 9.6 mW/°C.

TO252FP-5: In cases in which Ta≥25°C when a 70mm×70mm×1.6mm glass epoxy board is used, the power is reduced by 10.4 mW/°C.

TO220FP-5: No heat sink. When Ta≥25°C, the power is reduced by 16 mW/°C.

<sup>\*3</sup> Only for models with shutdown switches.
\*4 Applied voltage : 200msec or less (tr≥1msec)

#### **Electrical Characteristics**

BAxxCC0 Series (Unless otherwise specified, Ta=25°C, VcTL=5V, Io=500mA Setting \*5)

Parameter	Cumbal		Limit		Unit	Conditions
Parameter	Symbol	Min.	Тур.	Max.	Offic	Conditions
Output Voltage *6	Vo	Vo(T) × 0.98	Vo(T)	Vo(T) × 1.02	>	
Shut Down Current	Isd	ı	0	10	μΑ	VCTL=0V
Bias Current	lb	ı	2.5	5.0	mA	VCTL=2V, Io=0mA
Dropout Voltage	ΔVd	1	0.3	0.5	V	Vcc=Vo×0.95
Peak Output Current	lo	1.0	1	_	Α	
Ripple Rejection	R.R.	45	55	_	dB	f=120Hz, ein*7=1Vrms, lo=100mA
Line Regulation	Reg.I	ı	20	100	mV	Vcc=Vo(T)+1→25V
Load Regulation	Reg.L	1	50	150	mV	Io=5mA→1A
Temperature Coefficient of Output Voltage *8	Tcvo	ı	±0.02	_	%/°C	Io=5mA,Tj=0 to 125°C
Output Short Current	los	ı	0.40	_	Α	Vcc=25V
ON Mode Voltage	VthH	2.0		_	V	ACTIVE MODE, Io=0mA
OFF Mode Voltage	VthL	1	1	0.8	V	OFF MODE, Io=0mA
Input High Current	ICTL	100	200	300	μΑ	VCTL=5V, Io=0mA

BAxxDD0 series (Unless otherwise specified, Ta=25°C, VCTL=3V, Vcc=VccT\*9)

Denomination	0		Limit		11.2	0 4'0'
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Shut Down Current	Isd	_	0	10	μΑ	VCTL=0V, Io=0mA
Bias Current	lb	_	0.9	2.0	mA	lo=0mA
Output Voltage *10	Vo	Votyp × 0.99	Votyp	Votyp × 1.01	V	lo=200mA
Dropout Voltage 1 *11	∆Vd1	_	0.3	0.5	V	Vcc=0.95 × Vo, Io=1A
Dropout Voltage 2 *11	ΔVd2	_	0.45	0.7	V	Vcc=0.95 × Vo, Io=2A
Peak Output Current	lo	2.0	_	_	Α	
Ripple Rejection	R.R.	_	55	_	dB	f=120Hz, ein*7=-20dBV, Io=100mA
Line Regulation	Reg.I	_	15	50	mV	Vcc=VccT*9V→25V, Io=200mA
Load Regulation	Reg.L	_	50	200	mV	lo=0mA→2A
Temperature Coefficient of Output Voltage *8	Tcvo	_	±0.02	_	%/°C	Io=5mA, Tj=0 to 125°C
CTL ON Mode Voltage	Von	2.0	-	Vcc	V	ACTIVE MODE, Io=0mA
CTL OFF Mode Voltage	Voff	_	_	0.8	V	OFF MODE, Io=0mA
CTL Input Current	ICTL	_	60	120	μΑ	VCTL=3V, Io=0mA

<sup>\*5</sup> Vo=3.0V:Vcc=8.0V, 3.3V:Vcc=8.3V, Vo=5V:Vcc=10V, Vo=6V:Vcc=11V, Vo=7V:Vcc=12V, Vo=8V:Vcc=13V, Vo=9V:Vcc=14V, Vo=12V:Vcc=17V, Vo=15V:Vcc=20V

<sup>\*6</sup> Vo(T)=3.0, 3.3, 5.0, 6.0, 7.0, 8.0, 9.0,12, 15V

<sup>\*7</sup> ein : Input Voltage Ripple

<sup>\*8</sup> Not 100% tested

<sup>\*9</sup> Vo=1.5V,1.8V,2.5V,3.0V : Vcct =4.0V, Vo=3.3V,5.0V : Vcct =7.0V, Vo=9V : Vcct =12.0V, Vo=12V : Vcct =14.0V, Vo=16V : Vcct =18.0V)

<sup>\*10</sup> Votyp=1.5V,1.8V,2.5V,3.0V,3.3V,5.0V,9.0V,12.0V,16.0V

<sup>\*11</sup> Vo≧3.0V

#### **●**Typical Performance Curves

(Unless specified otherwise, Vcc=8.3V, Vo=3.3V, V<sub>CTL</sub>=5.0V, and Io=0mA) BAxxCC0xx (BA33CC0WT)

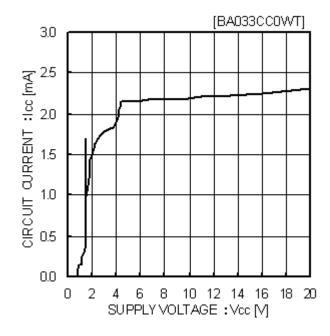


Fig.3 Circuit current

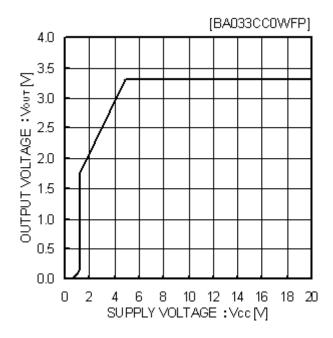


Fig.4 Input Stability

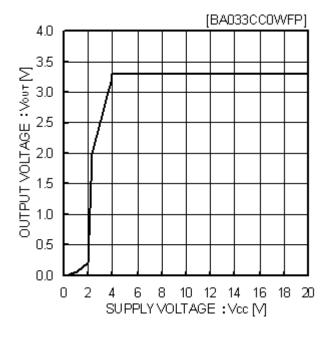


Fig.5 Input Stability (Io=500mA)

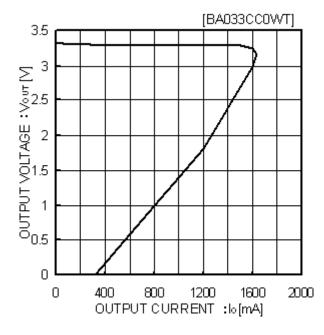


Fig.6 Load Stability

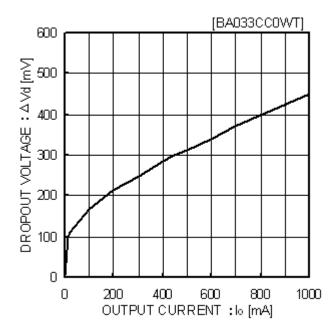


Fig.7
Input/Output Voltage Difference
Io-△Vd Characteristics (Vcc=2.95V)

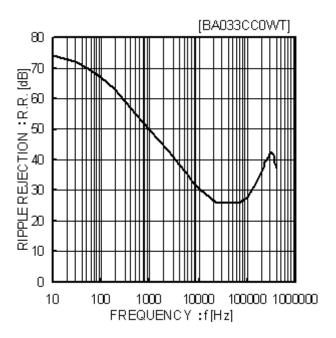


Fig.8
Ripple Rejection Characteristics
(Io=100mA)

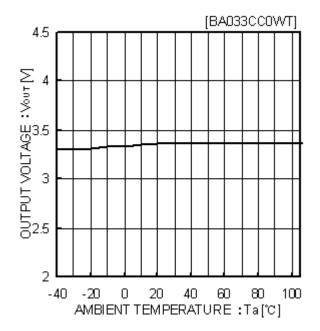


Fig.9 Output Voltage Temperature Characteristics

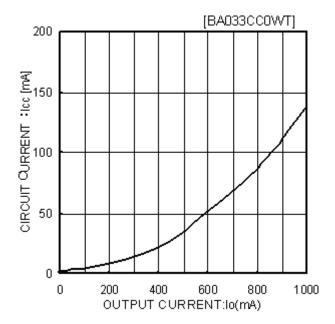


Fig.10 Circuit Current by load Level (Io∪t=0mA→1A)

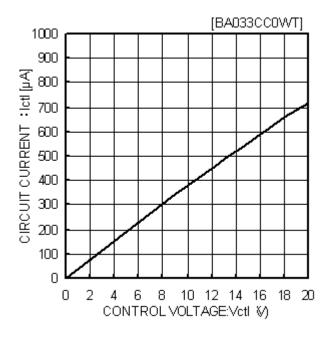


Fig.11
CTL Voltage vs. CTL Current

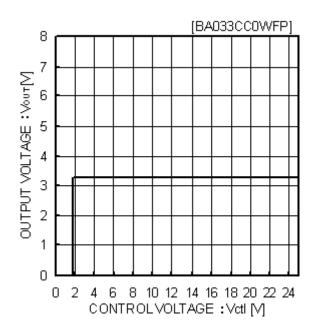


Fig.12 CTL Voltage vs. Output Voltage

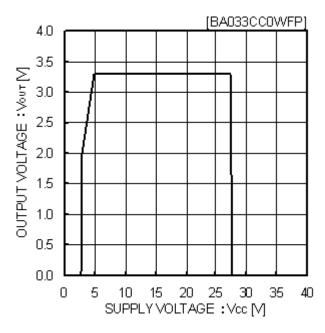


Fig.13
Overvoltage Operating
Characteristics (Io=200mA)

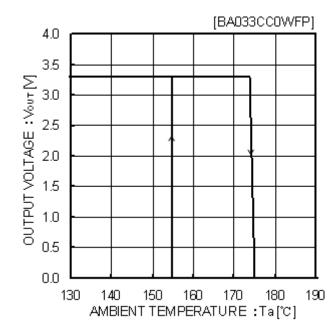


Fig.14
Thermal Shutdown
Circuit Characteristics

(Unless specified otherwise, Vcc=7.0V, Vo=5.0V, VcTL=3.0V, and Io=0mA) BAxxDD0xx (BA50DD0WT)

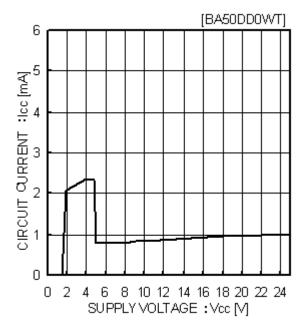


Fig.15 Circuit Current

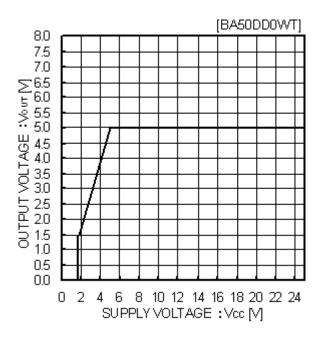


Fig.16 Input Stability (Io=0mA)

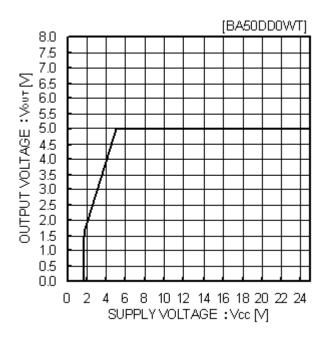


Fig.17
Input Stability (Io=2A)

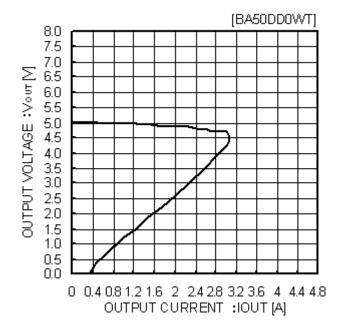


Fig.18 Load Stability

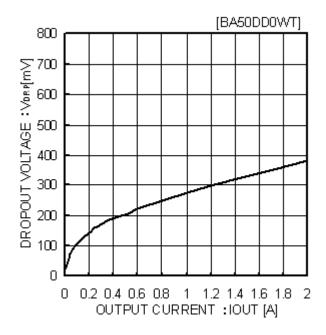


Fig.19
Input/Output Voltage Difference

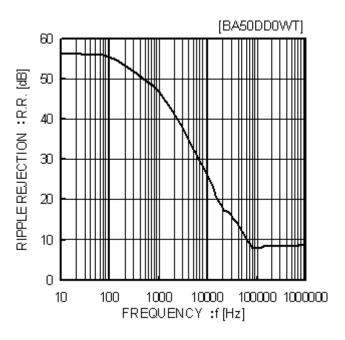


Fig.20 Ripple Rejection Characteristics

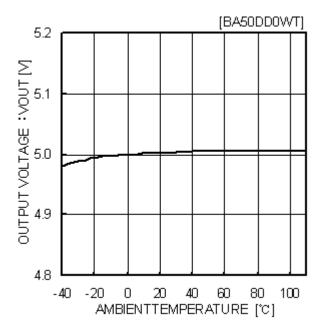


Fig.21
Temperature Characteristics

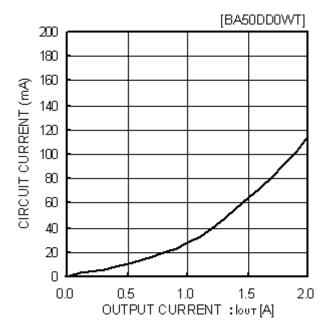


Fig.22 Circuit Current by Load Level (lout=0mA→2A)

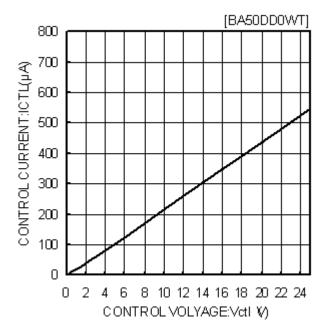


Fig.23 CTL Voltage vs. CTL Current

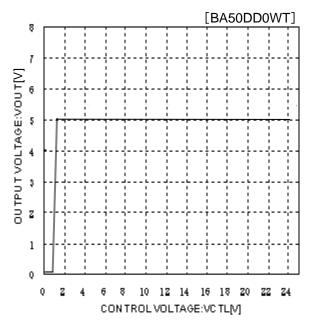


Fig.24 CTL Voltage vs. Output Voltage

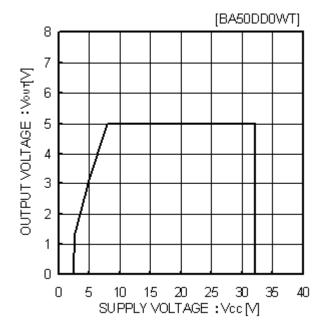


Fig.25 Overvoltage Operating (lo=200mA)

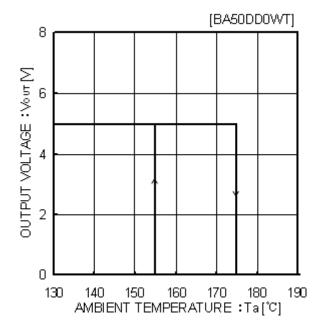
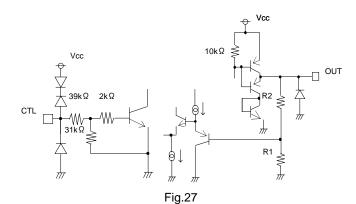


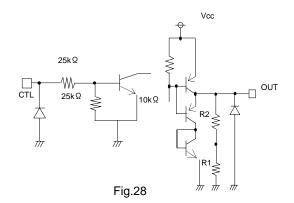
Fig.26
Thermal Shutdown
Circuit Characteristics

#### ●I/O equivalence circuit

#### <BAxxDD0xx Series>



#### <BAxxCC0xx Series>



#### Power Dissipation

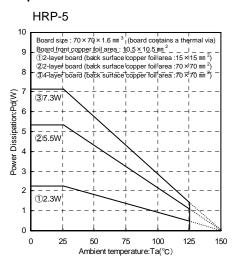


Fig.29

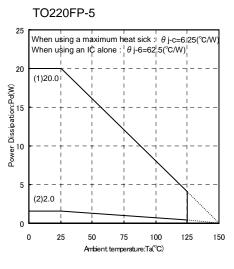
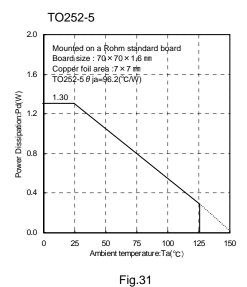


Fig.30



When using at temperatures over Ta=25°C, please refer to the heat reducing characteristics shown in Fig.29 through 31. The IC characteristics are closely related to the temperature at which the IC is used and if the temperature exceeds the maximum junction temperature TjMAX., the elements may be damaged or destroyed. From the standpoints of instantaneous destruction and long-term operating reliability, it is necessary give sufficient consideration to IC heat. In order to protect the IC from thermal damage, it is necessary to operate it at temperatures lower than the maximum junction temperature TjMAX of the IC.

Fig.30 shows the acceptable loss and heat reducing characteristics of the TO220FP package The portion shown by the diagonal line is the acceptable loss range that can be used with the IC alone. Even when the ambient temperature Ta is a normal temperature (25°C), the chip (junction) temperature Tj may be quite high so please operate the IC at temperatures less than the acceptable loss Pd.

The method of calculating the power consumption Pc (W) is as follows.

Vcc :Input voltage Vo :Output voltage lo :Load current Vcca :Circuit current

$$Pc = (Vcc-Vo) \times Io + Vcc \times Icca$$
  
Acceptable loss  $Pd \leq Pc$ 

Solving this for load current Io in order to operate within the acceptable loss:

$$lo \le \frac{Pd - Vcc \times Icca}{Vcc - Vo}$$
 (Please refer to Fig.10 and 22 for Icca.)

It is then possible to find the maximum load current IoMAX with respect to the applied voltage Vcc at the time of thermal design.

Calculation Example

Example 1) When Ta=85°C, Vcc=8.3V, Vo=3.3V, BA33DD0WT

$$lo ≤ \frac{1.04 - 8.3 \times lcca}{5}$$

$$lo ≤ 200mA (lcca : 2mA)$$
With the IC alone : θ ja=62.5°C/W → -16mW/°C 25°C=2000mW → 85°C=1040mW

Please refer to the above information and keep thermal designs within the scope of acceptable loss for all operating temperature ranges.

The power consumption Pc of the IC when there is a short circuit (short between Vo and GND) is:

Pc=Vcc × (Icca+Ishort) \*Ishort: Short circuit current

#### ●Peripheral Circuit Considerations

Vcc Terminal

Please attach a capacitor (greater than 0.33µF) between the Vcc and GND.

The capacitance values will differ depending on the application, so please take this into account when configuring the terminal.

GND Terminal

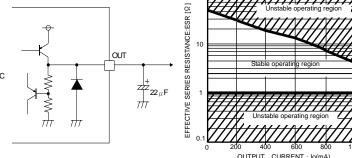
Please be sure to keep the set ground and IC ground at the same potential level so that a potential difference does not

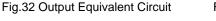
If a potential difference arises between the set ground and the IC ground, the preset voltage will not be outputted, causing the system to become unstable. Therefore, please reduce the impedance by making the ground patterns as wide as possible and by reducing the distance between the set ground and the IC ground as much as possible.

CTL Terminal

The CTL terminal is turned ON at 2.0V and higher and OFF at 0.8V and lower within the operating power supply voltage range. CC0xx series, the power supply and the CTL terminal in any order without problems.

#### Vo Terminal





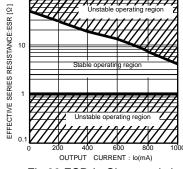


Fig.33 ESR-Io Characteristics (BAxxCC0)

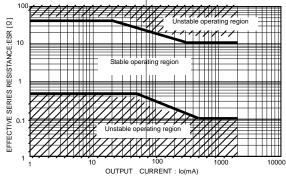


Fig.34 ESR vs. lo Characteristics (BAxxDD0)

Please attach an anti-oscillation capacitor between Vo and GND. The capacitance of the capacitor may significantly change due to factors such as temperature changes, making it impossible to completely stop oscillations. Please use a tantalum capacitor or aluminum electrolysis capacitor with favorable characteristics and small internal series resistance (ESR) even at low temperatures. The output fluctuates regardless of whether the ESR is large or small. Please use the IC within the stable operating region while referring to the ESR characteristics reference data shown in Fig.32 through 34. In applications where there are sudden load fluctuations, the use of a capacitor with large capacitance is recommended.

#### Operational Notes

1) Protection Circuits

#### Over-current Protection Circuit

A built-in over-current protection circuit corresponding to the current capacity prevents the destruction of the IC when there are load shorts. This protection circuit is a "7"-shaped current control circuit that is designed such that the current is restricted and does not latch even when a large current momentarily flows through the system with a high-capacitance capacitor. However, while this protection circuit is effective for the prevention of destruction due to unexpected accidents, it is not suitable for continuous operation or transient use. Please be aware when creating thermal designs that the overcurrent protection circuit has negative current capacity characteristics with regard to temperature (Refer to Fig.6 and 18).

#### Thermal Shutdown Circuit (Thermal Protection)

This system has a built-in temperature protection circuit for the purpose of protecting the IC from thermal damage.

As shown above, this must be used within the range of acceptable loss, but if the acceptable loss happens to be continuously exceeded, the chip temperature Tj increases, causing the temperature protection circuit to operate.

When the thermal shutdown circuit operates, the operation of the circuit is suspended. The circuit resumes operation immediately after the chip temperature Tj decreases, so the output repeats the ON and OFF states (Please refer to Fig.14 and 26 for the temperatures at which the temperature protection circuit operates).

There are cases in which the IC is destroyed due to thermal runaway when it is left in the overloaded state. Be sure to avoid leaving the IC in the overloaded state.

#### Reverse Current

In order to prevent the destruction of the IC when a reverse current flows through the IC, it is recommended that a diode be placed between the Vcc and Vo and a pathway be created so that the current can escape (Refer to Fig.35).

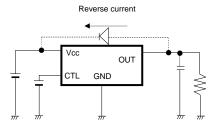


Fig.35 Bypass diode

2) This IC is bipolar IC that has a P-board (substrate) and P+ isolation layer between each devise, as shown in Fig.36. A P-N junction is formed between this P-layer and the N-layer of each device, and the P-N junction operates as a parasitic diode when the electric potential relationship is GND> Pin A, GND> Pin B, while it operates as a parasitic transistor when the electric potential relationship is Pin B GND> Pin A. Parasitic devices are structurally inevitable in the IC. The operation of parasitic devices induces mutual interference between circuits, causing malfunctions and eventually the destruction of the IC. It is necessary to be careful not to use the IC in ways that would cause parasitic elements to operate. For example, applying a voltage that is lower than the GND (P-board) to the input terminal.

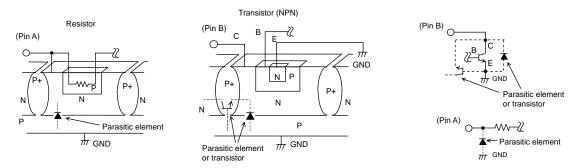


Fig.36 Example of the basic structure of a bipolar IC

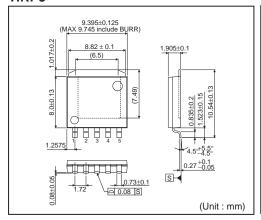
#### Status of this document

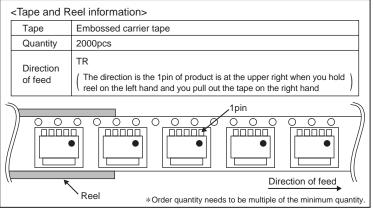
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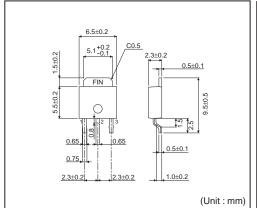
#### Physical Dimension Tape and Reel Information

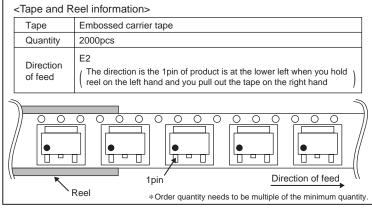
#### HRP5



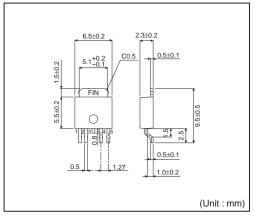


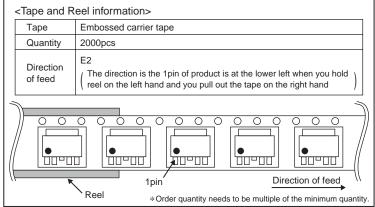
#### TO252-3



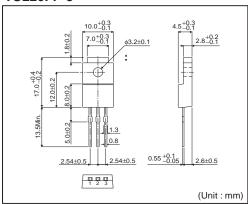


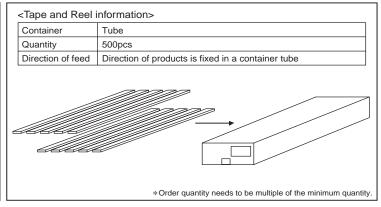
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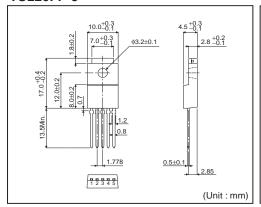


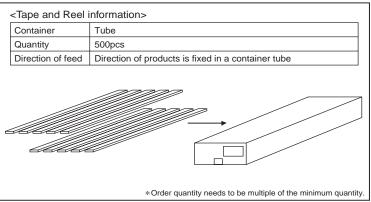
#### TO220FP-3



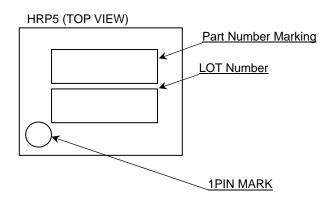


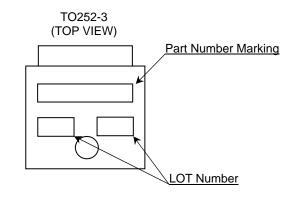
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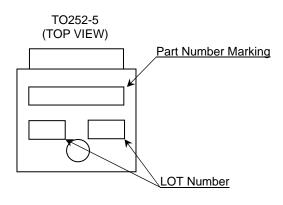


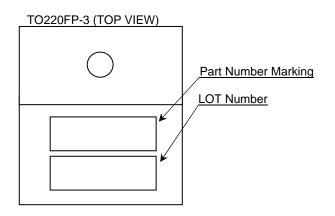


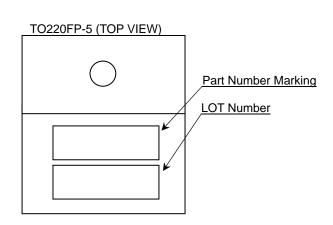
#### Marking Diagrams











■1A output BAxxCC0xx	x Series	
Orderable Part Number	Package	Part Number Marking
BA033CC0WFP-E2		033CC0W
BA05CC0WFP-E2		05CC0W
BA06CC0WFP-E2		06CC0W
BA07CC0WFP-E2	TO252-5	07CC0W
BA08CC0WFP-E2		08CC0W
BA09CC0WFP-E2		09CC0W
BAJ2CC0WFP-E2		J2CC0W
BA03CC0WT		03CC0W
BA033CC0WT		033CC0W
BA05CC0WT		05CC0W
BA07CC0WT	TOSSOED 5	07CC0W
BA08CC0WT	TO220FP-5	08CC0W
BA09CC0WT		09CC0W
BAJ0CC0WT		J0CC0W
BAJ2CC0WT		J2CC0W
BA03CC0FP-E2		03CC0
BA033CC0FP-E2		033CC0
BA05CC0FP-E2		05CC0
BA06CC0FP-E2		06CC0
BA07CC0FP-E2	TO252.2	07CC0
BA08CC0FP-E2	TO252-3	08CC0
BA09CC0FP-E2		09CC0
BAJ0CC0FP-E2		J0CC0
BAJ2CC0FP-E2		J2CC0
BAJ5CC0FP-E2		J5CC0
BA03CC0T		03CC0
BA033CC0T		033CC0
BA05CC0T		05CC0
BA06CC0T		06CC0
BA07CC0T	TO220FP-3	07CC0
BA08CC0T	10220FF-3	08CC0
BA09CC0T		09CC0
BAJ0CC0T		J0CC0
BAJ2CC0T		J2CC0
BAJ5CC0T		J5CC0

■2A output BAxxDD0xx		
Orderable Part Number	Package	Part Number Marking
BA15DD0WT		15DD0W
BA18DD0WT		18DD0W
BA25DD0WT		25DD0W
BA30DD0WT	TO220FP-5	30DD0W
BA33DD0WT		33DD0W
BA50DD0WT		50DD0W
BA90DD0WT		90DD0W
BAJ2DD0WT		J2DD0W
BAJ6DD0WT		J6DD0W
BA15DD0WHFP-TR		15DD0W
BA18DD0WHFP-TR		18DD0W
BA25DD0WHFP-TR		25DD0W
BA30DD0WHFP-TR		30DD0W
BA33DD0WHFP-TR	HRP5	33DD0W
BA50DD0WHFP-TR		50DD0W
BA90DD0WHFP-TR		90DD0W
BAJ2DD0WHFP-TR		J2DD0W
BAJ6DD0WHFP-TR		J6DD0W
BA15DD0T		15DD0
BA18DD0T		18DD0
BA25DD0T		25DD0
BA30DD0T		30DD0
BA33DD0T	TO220FP-3	33DD0
BA50DD0T		50DD0
BA90DD0T		90DD0
BAJ2DD0T		J2DD0
BAJ6DD0T		J6DD0

#### Revision History

Date	Revision	Changes					
26.Jun.2012	001	New Release					
25.July.2013	002	Page-14 Changed CTL terminal description					
9.Aug.2013	003	Page-6 Added comment "Vo=3.0C:Vcc=8.0V", "Vo=15V:Vcc=20V" in *5 Page-6 Added comment "3", "15V" in *6					

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JAPAN	USA	EU	CHINA
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CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [d] the Products are exposed to high Electrostatic
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